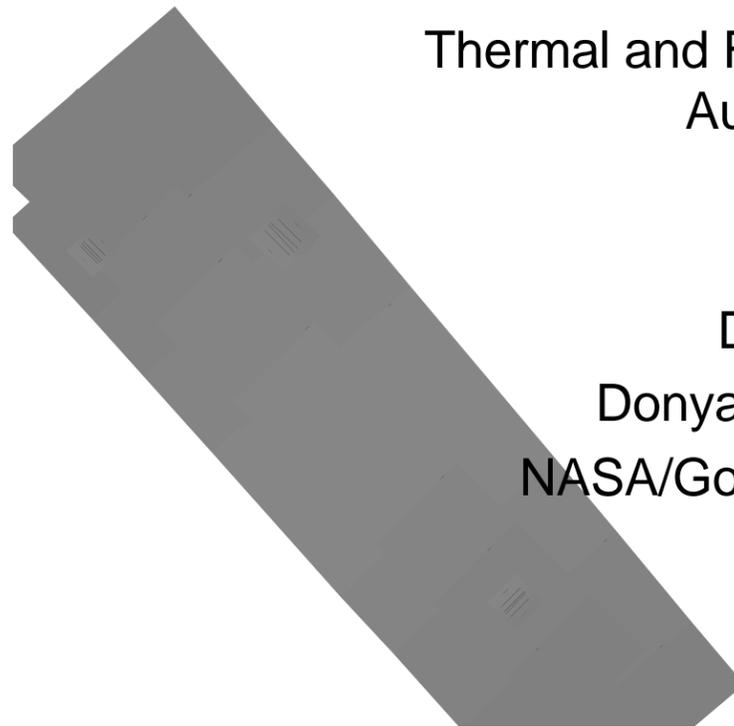




# VARIABLE EMITTANCE COATINGS FOR THERMAL CONTROL

Thermal and Fluids Analysis Workshop 2003  
August 18 – 22, 2003  
Hampton, VA

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NASA/Goddard Space Flight Center





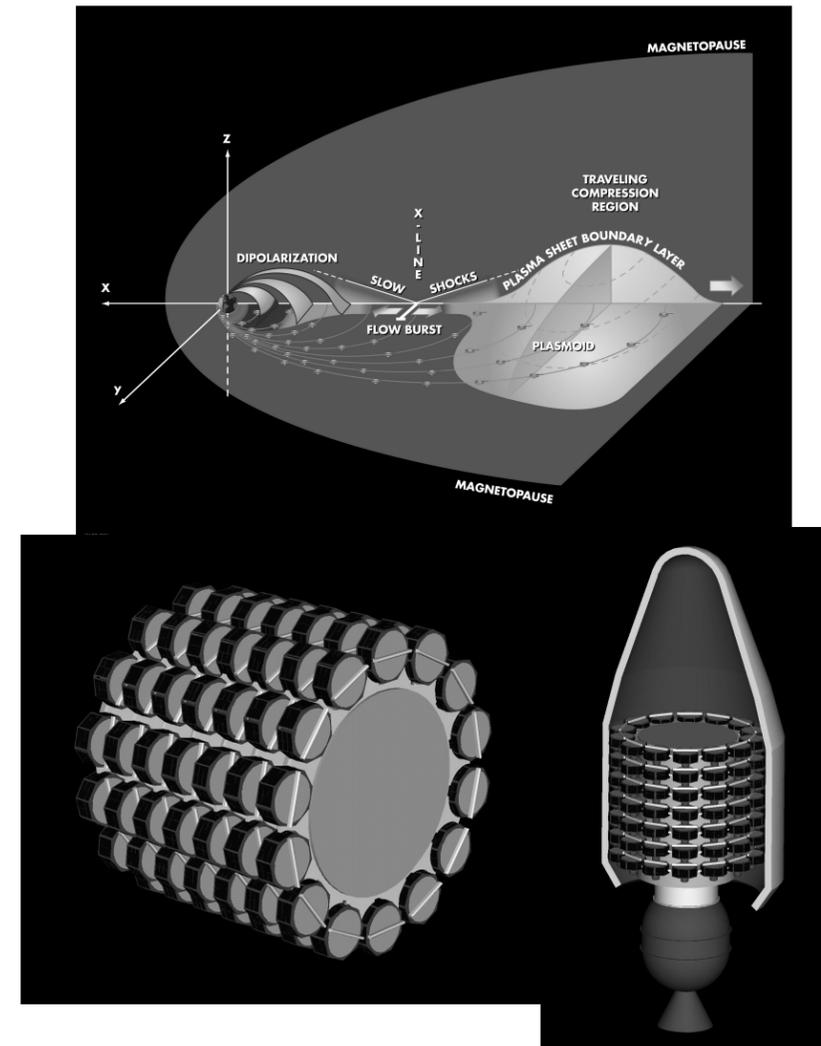
# Agenda

- Background
- ST-5 Flight Opportunity
- Overview of Variable Emittance Coatings
- Development of VEC Technologies for ST-5
- Major Issues/Concerns



# Background

- Future missions such as DRACO want to determine how the magnetotail stores, transports, and releases matter and energy:
  - Include fleets of 50 to 100 satellites
  - Elliptical orbits with dense sampling from 7 - 40 RE
- Unique thermal control problems:
  - Low mass result in large temperature variations
  - Power limited
  - Extreme environments – up to 8 hour eclipses
- *Need means of modulating heat rejection rate*



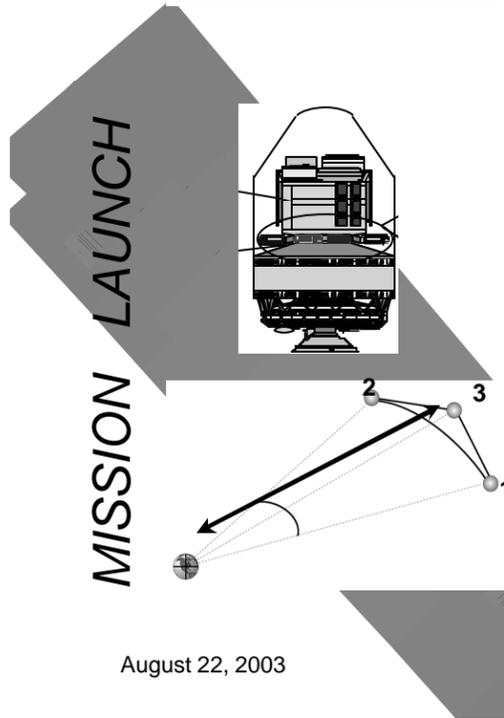
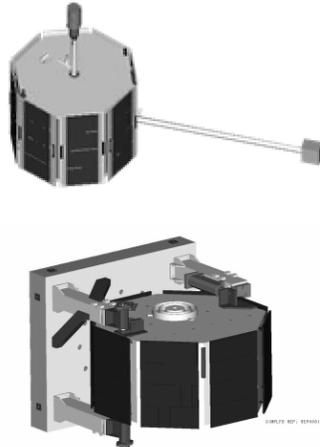


# Space Technology 5: Technology Validation Mission

- ST5 is a constellation of three spacecraft whose level one requirements are to:
  - Design, develop, integrate, test and operate three full service spacecraft, each with a mass less than 25kg, through the use of breakthrough technologies
  - Demonstrate the ability to achieve accurate, research-quality scientific measurements utilizing a nanosatellite with a mass less than 25 kg
  - Execute the design, development, test and operation of multiple spacecraft to act as a single constellation rather than as individual elements
- Primary Technology Thrusts:
  - High performance, low mass
  - Low power, low voltage, rad-tolerant electronics
  - Low cost manufacturing & testing techniques
  - Autonomy for both onboard & ground operations
  - Scalable



SPACECRAFT

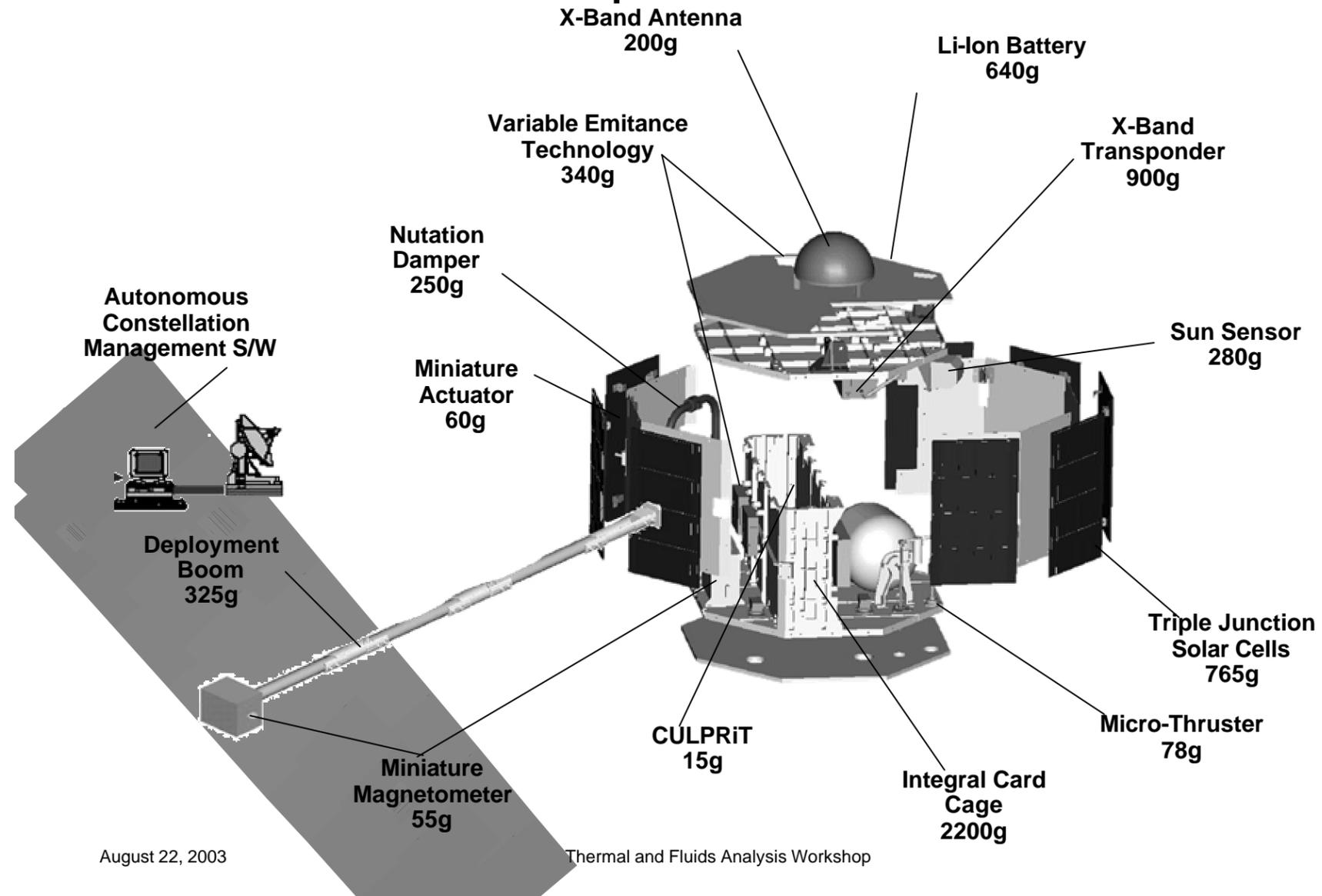


# Space Technology 5 Mission Summary

- Full Functional Autonomous Spacecraft with Integrated Technology Development
- Science Grade Magnetic Sensitivity ( $\sim 0.2\text{nT}$ )
- Mass:  $\approx 25\text{Kg}$
- Size: Diameter  $\sim 50.8\text{ cm}$  (Flat-to-Flat)  
Height  $\sim 27.6\text{ cm}$  (Deck-to-Deck)
- Power:  $\sim 21.5\text{W}$  (Usable for Load)  
 $\sim 7.5\text{ Ah}$  Battery
- Uplink: @  $1\text{Kbps}$  / Downlink: @  $1\text{Kbps}$  or  $100\text{Kbps}$  (X-Band)
- Data Storage:  $20\text{ Mbyte}$
- Spin Stabilized at Separation ( $\sim 25\text{ RPM}$  After Deployments)
- Deployments: Magnetometer
- Radiation Tolerant:  $100\text{Krad-Si}/3\text{ Months}$
  
- Ride: Boeing Delta IV or Lockheed Atlas V
- Orbital Injection: Geosynchronous Transfer Orbit ( $240 \times 37,000\text{Km}$ )
- Secondary Payload
  
- 3-Spacecraft Constellation
- 3-Month Design Life
- $\sim 11\text{ Hr}$  Orbit Period
- 20-30 Minute Ground Contact Per Orbit
- Autonomous Constellation Management / "Lights Out" Operations



# Space Technology 5 Spacecraft



August 22, 2003

Thermal and Fluids Analysis Workshop

6



# Space Technology 5 Development Status

- Schedule
  - Component level qualification testing underway.
  - November 2003 – Spacecraft 1 I&T
  - December 2004 – Launch Readiness Date
- ST-5 technologies already being infused into future missions
  - THEMIS – Sun Sensor
  - DAWN – Propulsion tank
  - GEC -- Mag boom
  - MagCon – Entire spacecraft bus



# Variable Emittance Coatings Overview (1 of 3)

- Variable Emittance Coatings (VEC) have been under development at GSFC since the mid-1990's:
  - Electrochromically actuated polymers
    - Under development by Ashwin Ushas Co., Inc.
    - TRL 3
    - Had difficulty surviving vacuum
  - Electrostatically actuated flaps
    - Under development by Sensortex, Inc.
    - Flying on ST-5
    - TRL 6
  - Micro Electro-Mechanical Systems (MEMS) “Mini Shutters”
    - Under development by JHU APL and Sandia National Laboratory
    - Flying on ST-5
    - TRL 6



# Variable Emittance Coatings Overview (2 of 3)

- Benefits
  - By changing the effective infrared emittance of the surface, they allow the radiative heat transfer rate to be modulated upon command
  - Significant benefits identified by systems level studies on representative spacecraft. For a 6:1 variation in  $e^*$  :
    - 50 – 90% heater power savings
    - Similar mass/cost savings over VCHP/louver applications
  - Major reductions in component temperature variations will lead to improved reliability
  - VEC coatings generically useful for all S/C, but especially suitable for small S/C and fleets of small S/C
    - VEC coatings very lightweight and negligible power consumption
    - VEC coatings provide a flexible design solution; do not need customized thermal design for all S/C in a fleet

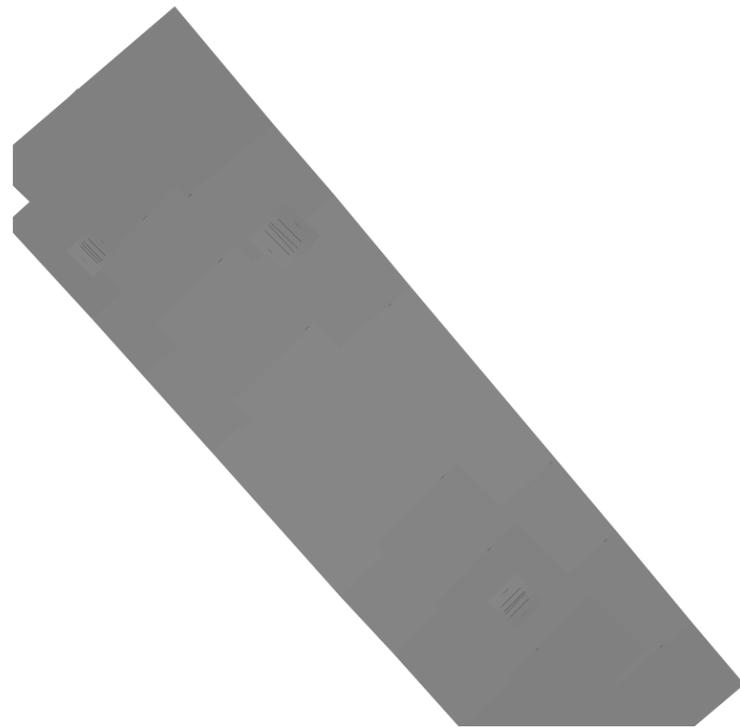


# Variable Emittance Coatings Overview (3 of 3)

- Development Participants
  - NASA/GSFC
  - JPL
  - Johns Hopkins University Applied Physics Lab
  - Sandia National Laboratories
  - Sensortex Corp.
  - Air Force Research Laboratory
  - Ashwin-Ushas Corp.
- Co-Funding Sources
  - JPL
  - APL/Johns Hopkins University
  - DoE/Sandia National Laboratories
  - DoD/Air Force RL
  - NASA SBIR Program



# Development of VEC Technologies for ST-5





# Objectives

- Develop highly innovative thermal control coatings which can repeatedly change their properties in response to an external signal
  - To validate the technologies as part of the spacecraft thermal control system
  - Demonstrate variable emittance range of 0.2 to 0.8
- Program currently includes two alternative concepts (MEMS and Electrostatic) with both ground testing and flight experiment verification
- Each spacecraft will carry two different VEC radiators-one on the top deck and the other on the bottom
- Goal is to mature technologies to TRL 9 - Perception is that each concept has different advantages and applications
- Demonstrate survival in harsh space environment (UV, solar wind micrometeoroid, hard vacuum, temperature cycling, etc.)
- Determine lifecycle cost: device itself, design effort, I&T issues, etc.



# General Requirements

- Package Requirements
  - Total weight shall not exceed 350g
    - This mass limit includes radiator, electronics, mounting and support hardware, cables, and instrumentation.
  - Radiator assembly constrained to a 10 cm (L) x 9 cm (W) x 3 cm (H) footprint.
  - ECU will be housed in a 8.77cm x 8.77cm x 3.91 cm package
- Power Requirements
  - The controller (ECU) is powered by 5.23V  $\pm$  0.1V supply from Electrical Power System
  - Allocated Power
    - 217 mW nominal and 365 mW maximum - to drive controller and to actuate the ESR radiator



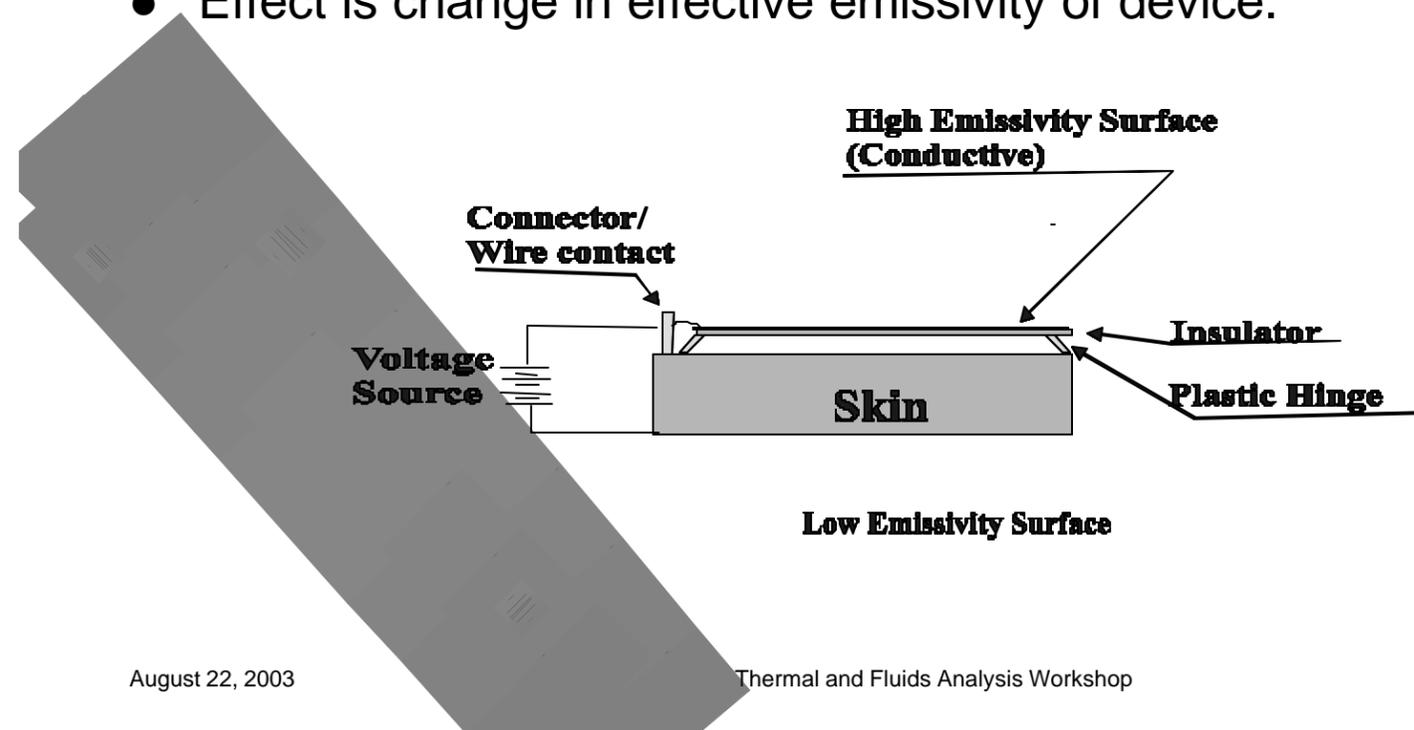
# Electrostatically Acutated Flaps Project Organization

- Technology being developed by Sensortex, Inc located in Pennsylvania with a subcontract to JHU APL for the control electronics.
- Funding Source: Phase I and II SBIRs
- Project Manager – William Biter
  - Project management interface with NASA GSFC and JHU APL
  - Overall project management & schedule / budget compliance
  - E-mail: [wbiter@sensortex.com](mailto:wbiter@sensortex.com)
  - (610)444-2383
- Stephen Hess
  - Operational interface with NASA GSFC and JHU APL
  - E-mail: [smhess@sensortex.com](mailto:smhess@sensortex.com)



# Electrostatically Acutated Flaps Technology Overview

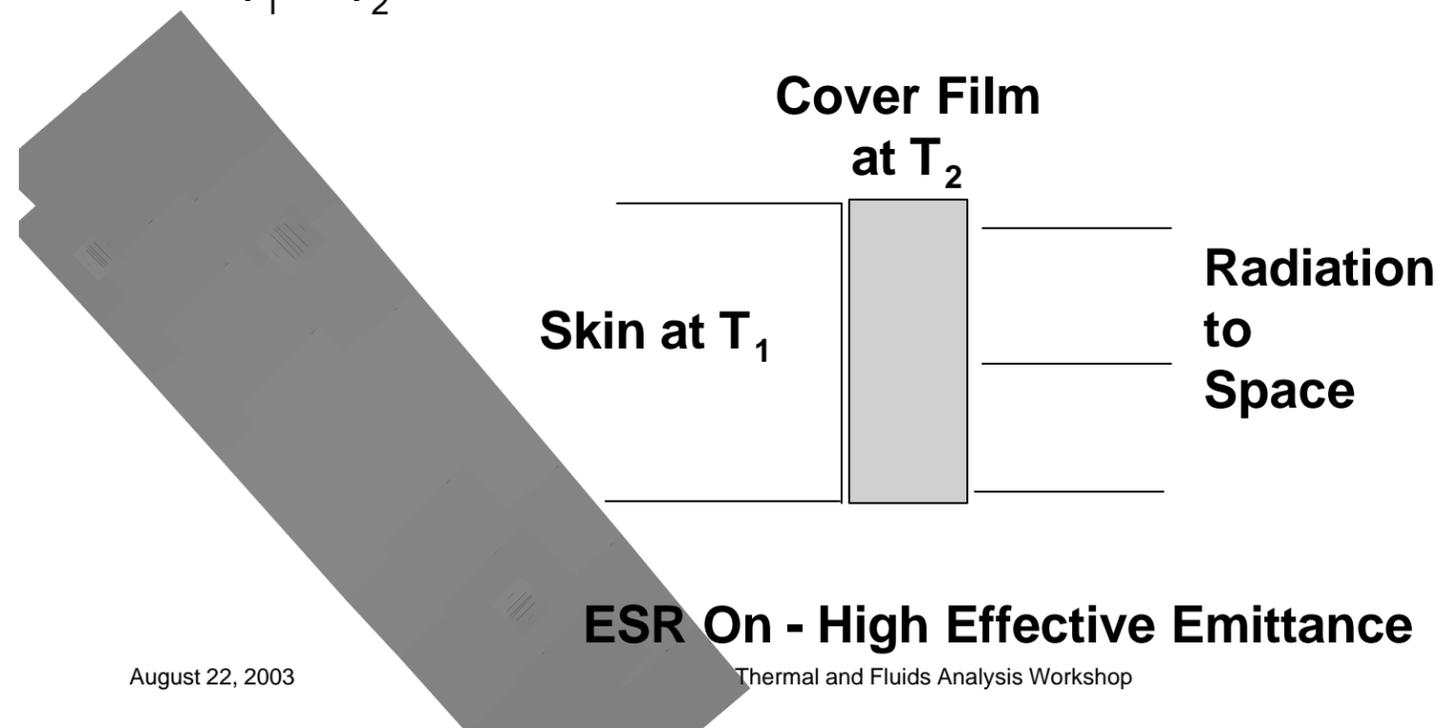
- Simple approach to control radiation.
- Thin conformal membrane (cover) is attracted to skin using electrostatic forces produces intimate contact.
- Thermal transfer from spacecraft skin to emissive film switches from conduction to radiation.
- Effect is change in effective emissivity of device.





# Electrostatically Acutated Flaps Operational Approach

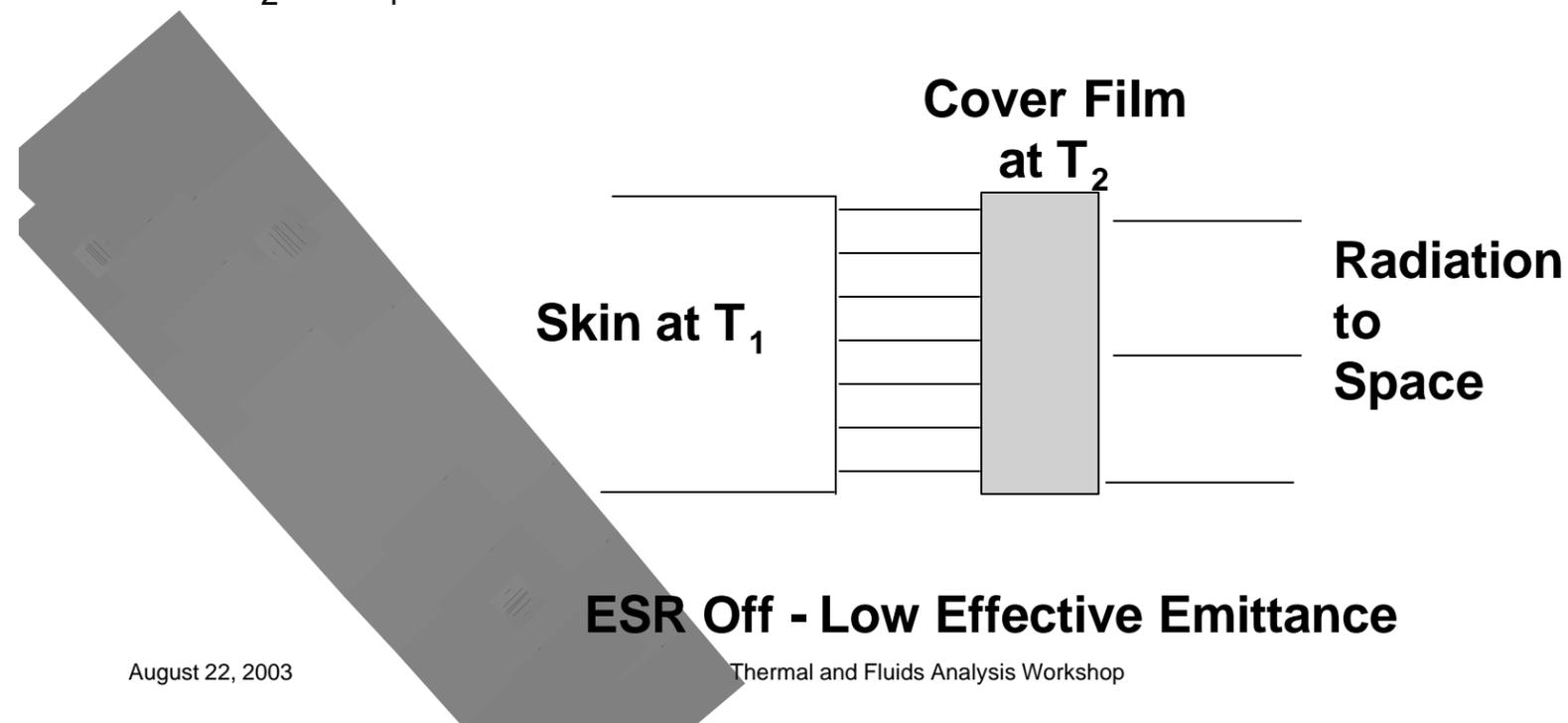
- ESR On State - High Effective Emittance
  - Film in good thermal contact with spacecraft skin.
  - Heat transfer from spacecraft skin to ESR via conduction.
  - High emissivity cover radiates energy to space.
  - $T_1 = T_2$





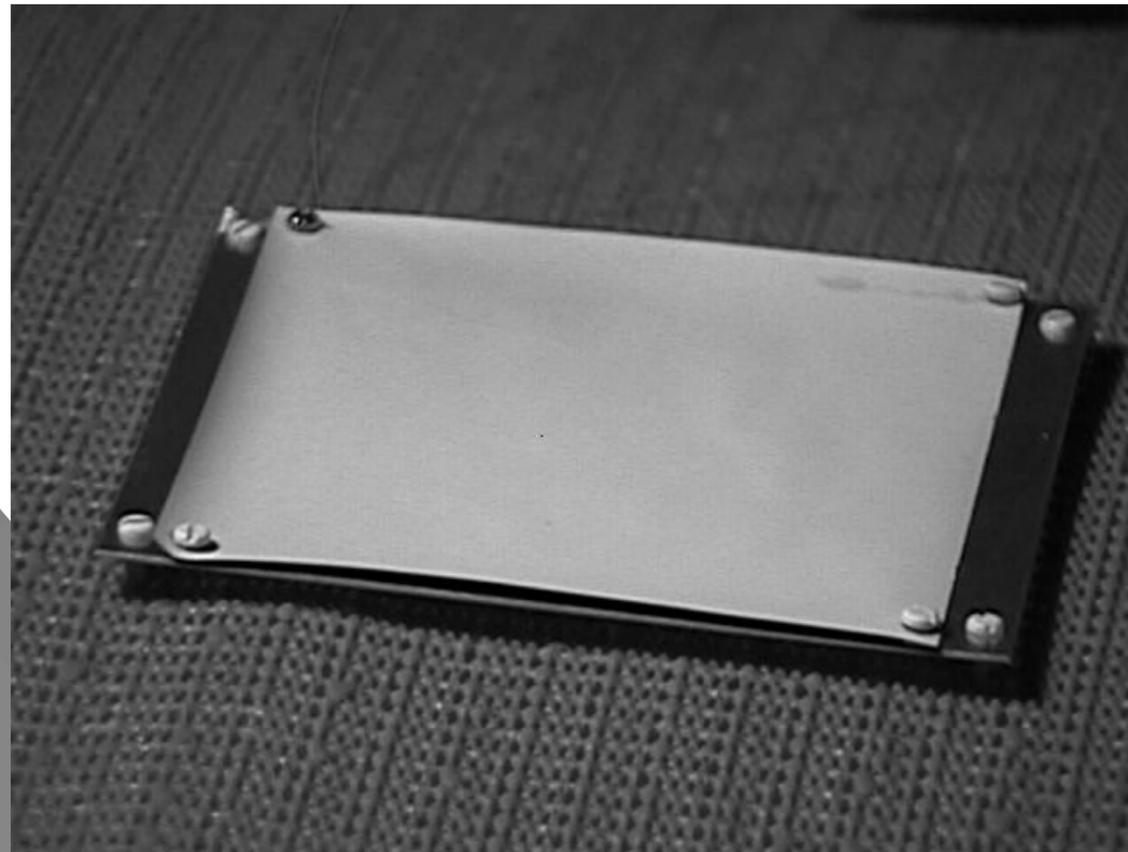
# Electrostatically Acutated Flaps Operational Approach

- ESR Off State - Low Effective Emittance
  - Film not in thermal contact with spacecraft skin.
  - Radiation heat exchange between skin and film cover
  - Spacecraft and underside of film have low emittance properties
  - $T_2 \ll T_1$





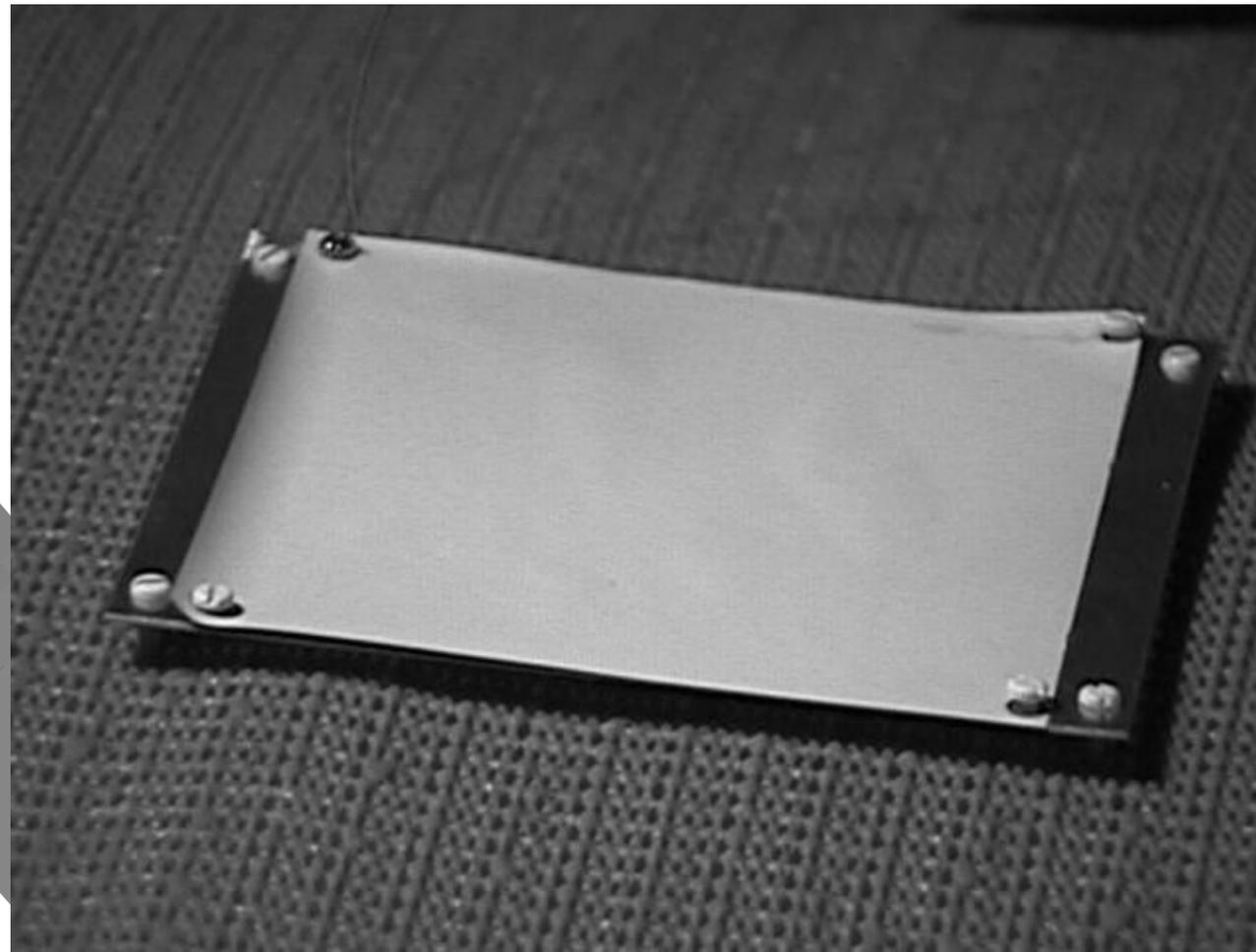
# Electrostatically Actuated Flaps ESR "Off" - No Applied Voltage





# Electrostatically Actuated Flaps

## ESR "On" – 400 Volts Applied

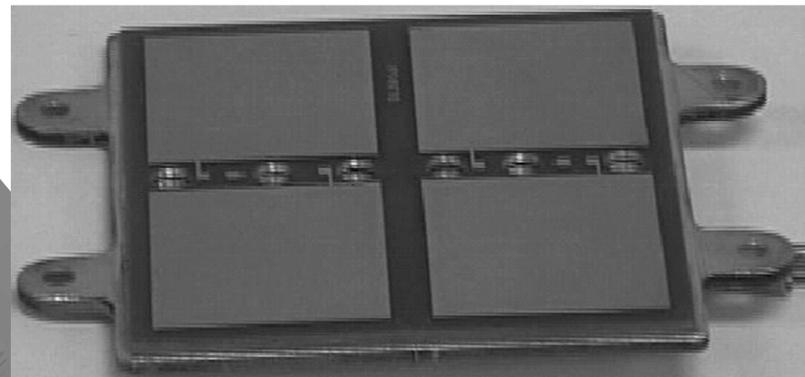




# Electrostatically Actuated Flaps

## Current Status

- Operating cells fabricated and tested.
  - Large observed changes in emissivity during cold (LN2 temperature) thermal vacuum testing.
  - Consistently obtain active area emissivity changes  $> .6$  at 99% confidence level.
  - Cells tested with more than 10,000 operating cycles (limited test conditions).
  - Demonstrated ability to control the four active areas
- Flight substrates fabricated and assembly underway.
- Electronic control unit under fabrication





# Electrostatically Acutated Flaps

## Milestone/Schedule

- All milestones consistent with and support ST-5 project schedule.
- Electronics breadboard to NASA for FLATSAT testing – 28 February 2003.
- October - November 2003 - Qualification Testing of Unit 1
- November - December 2003 - Acceptance Testing of Units 2 and 3
- December 2003 – Unit 1 shipped to GSFC
- January 2004 – Units 2 and 3 shipped to GSFC



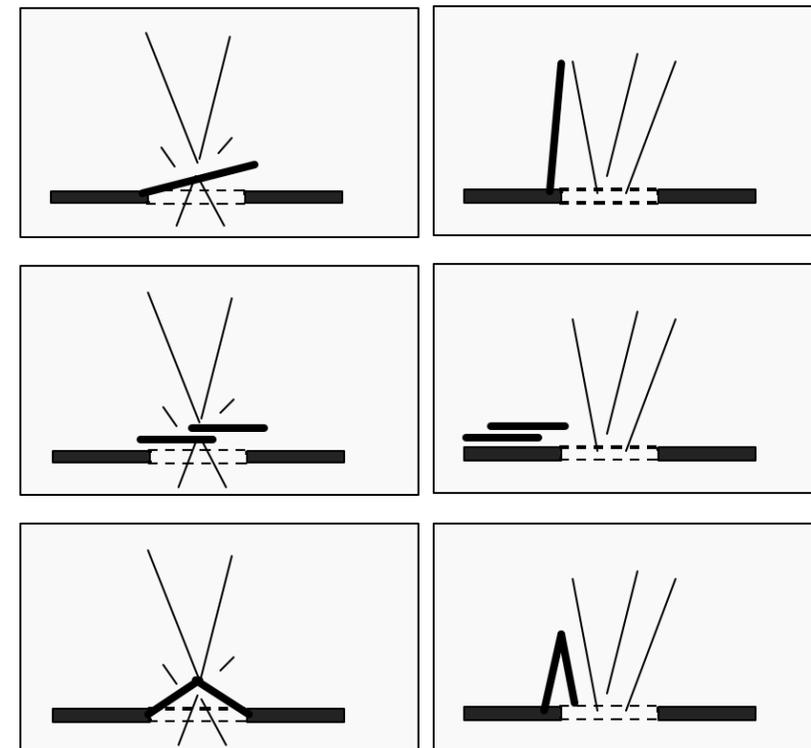
# MEMS Shutters Project Organization

- Technology being developed by JHU APL
- Funding Source: Internal Funding and subsequent contract
- Project Manager – Ann Darrin
  - Project management interface with NASA GSFC
  - Overall project management & schedule/budget compliance
  - E-mail: [Ann.Darrin@jhuapl.edu](mailto:Ann.Darrin@jhuapl.edu)
  - (240) 228 – 4952
- Robert Osiander
  - Responsible for radiator development
  - E-mail: [Robert.Osiander@jhuapl.edu](mailto:Robert.Osiander@jhuapl.edu)
- Dawnielle Farrar
  - Responsible for control electronics
  - E-mail: [Dawnielle.Farrar@jhuapl.edu](mailto:Dawnielle.Farrar@jhuapl.edu)



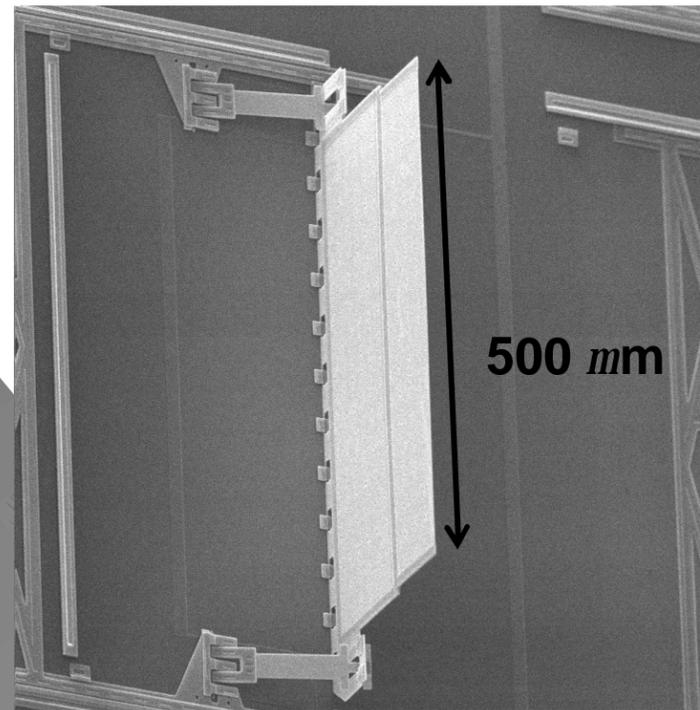
# MEMS Technology Overview

- Micromachined devices which are similar in function and design to conventional mechanical louvers where a mechanical vane or window is opened and closed to vary the radiative view to space
- Expected emittance changes of  $\Delta e = 0.8$
- Emittance will be remotely controlled with low power electrostatic drive.
- Three concepts
  - Louvers
  - Sliders
  - Folders
- Each design has its limitation

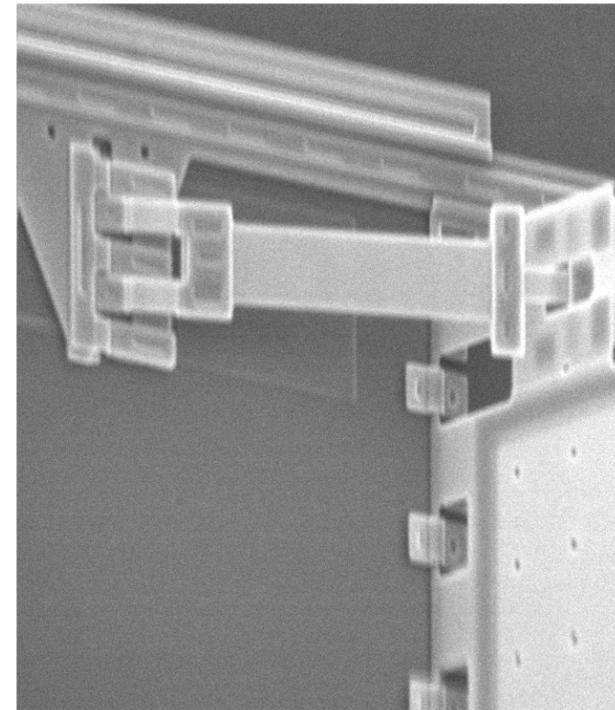




# MEMS Louvers SEMs of First Design



**Open Louver**

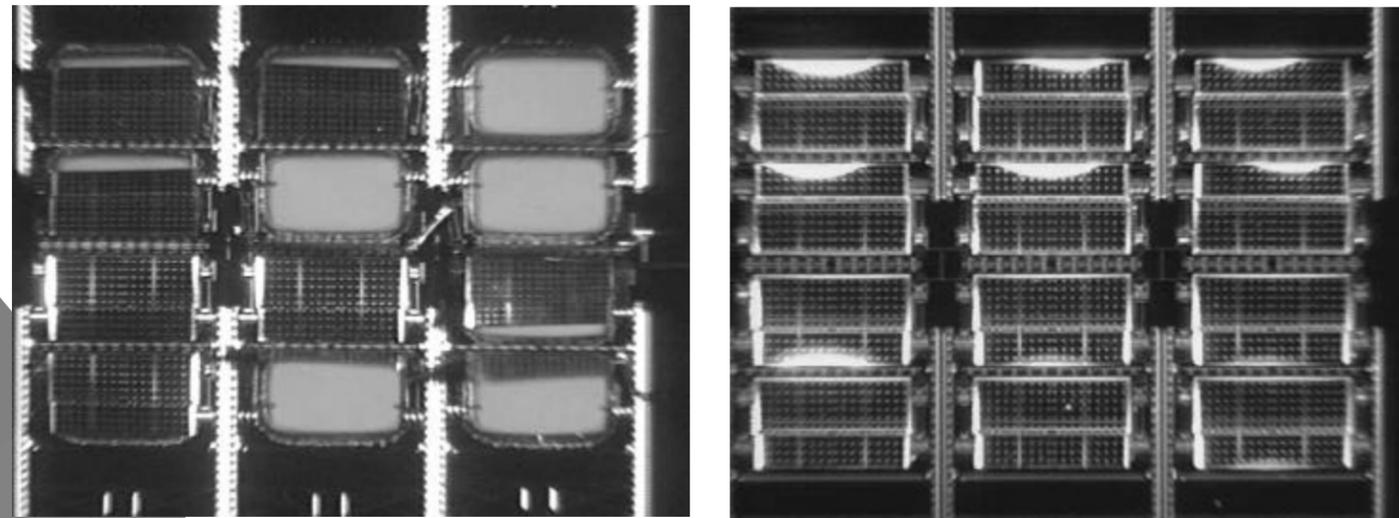


**Hinge Detail**



# MEMS Louvers

## Optical Image of First Design

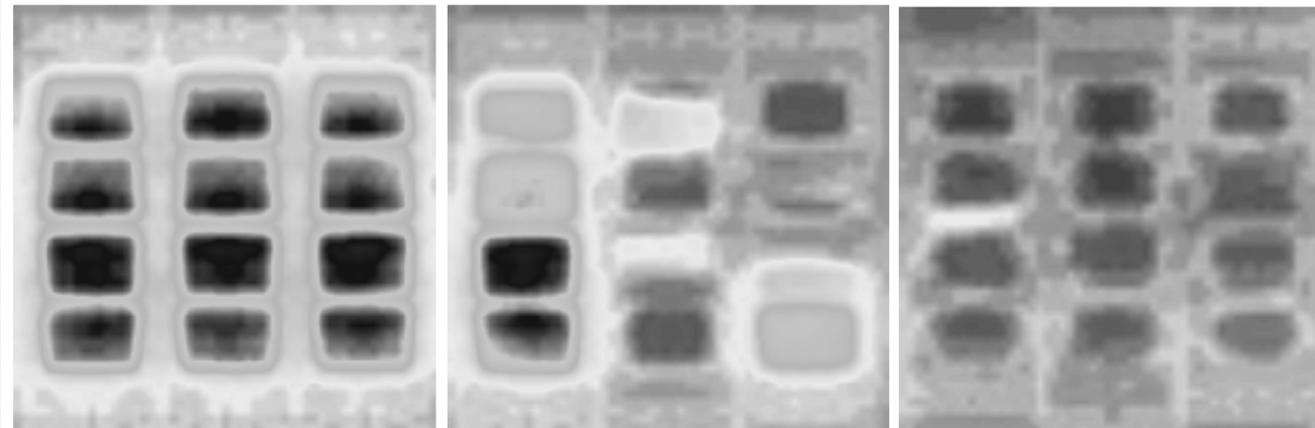
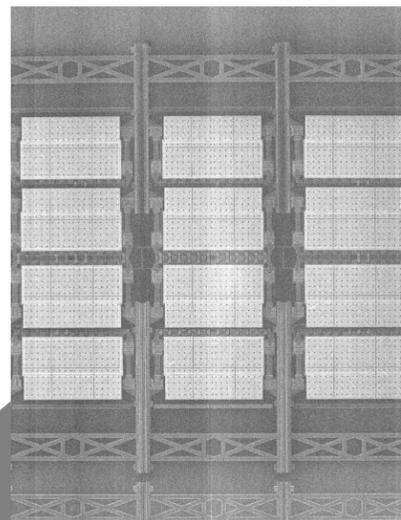


**Optical Image of a Louver Array, With Open Louvers (Left) and All Louvers Closed (Right). The Open Louvers Expose the Radiator (Gray Background) Through the Etched Openings.**



# MEMS Louvers

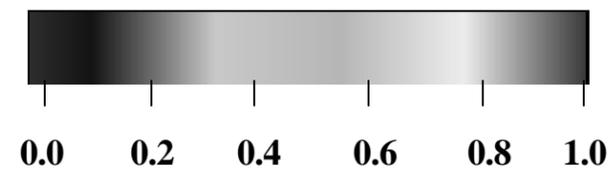
## IR Measurements of First Design



Closed-----Partially Open-----Open

### Louver Array Emissivity:

<b>Closed</b>	<b>0.5</b>
<b>Partially Open</b>	<b>0.75</b>
<b>Open</b>	<b>0.88</b>



**Emissivity (3-5 mm)**



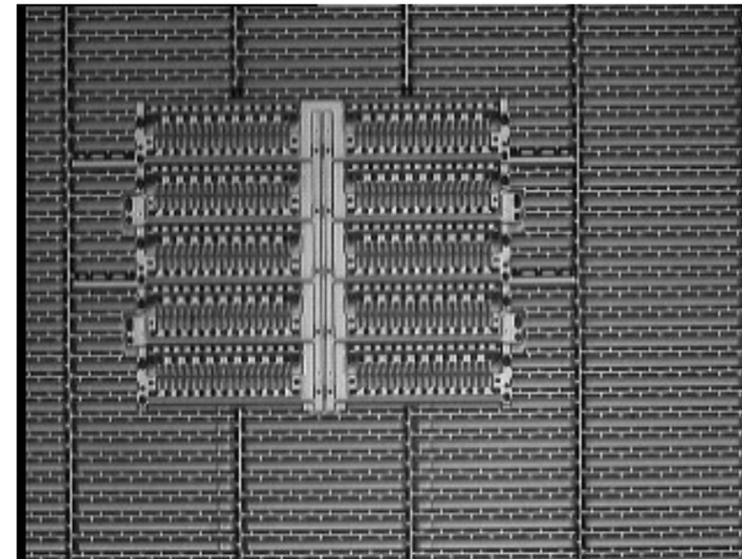
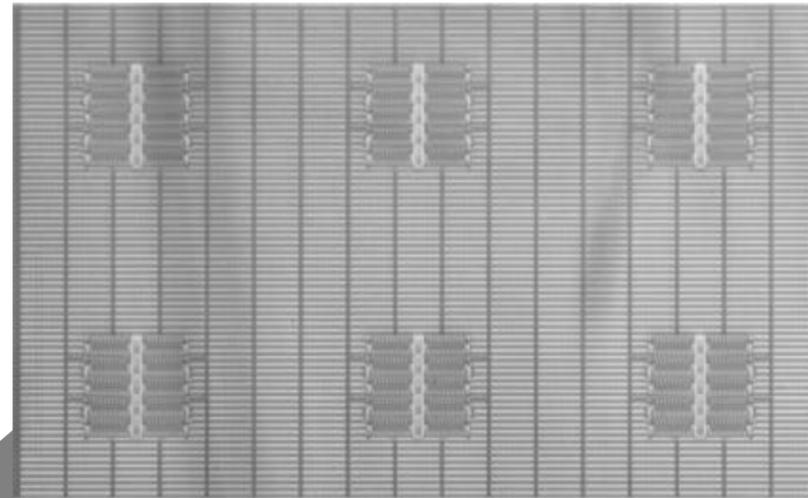
# MEMS Shutters

## Final Design Selection

- Development issues resulted in shutter design
  - Low Power Electrostatic comb drive required Sandia's 5-Layer Special SUMMiT V MEMS Process (comb drive footprint only 10 % of Area)
  - Turnaround time for the special SUMMiT V with buried interconnects is very long (9-12 months) - only one prototype run possible
  - Emissivity change limited by design to 40 % (eHigh - eLow)
- MEMS Shutter Design
  - No Friction design
  - All ground design
  - High and low emissivity limited to the properties of MEMS materials and coatings (Gold, Silicon)



# MEMS Shutters Basic Design



- Shutters and Slits: 6 mm x 150 mm
- Die Design Area: 11.8 x 11.8 mm
- Active Area: 1.12 cm<sup>2</sup>
- Diced Die: (12.65 x 13.03 mm) 1.65 cm<sup>2</sup>
- 9 Building Block: 1.77 mm x 0.88 mm, driven simultaneously by 6 comb drive units
- Design repeatable over 6 in wafer

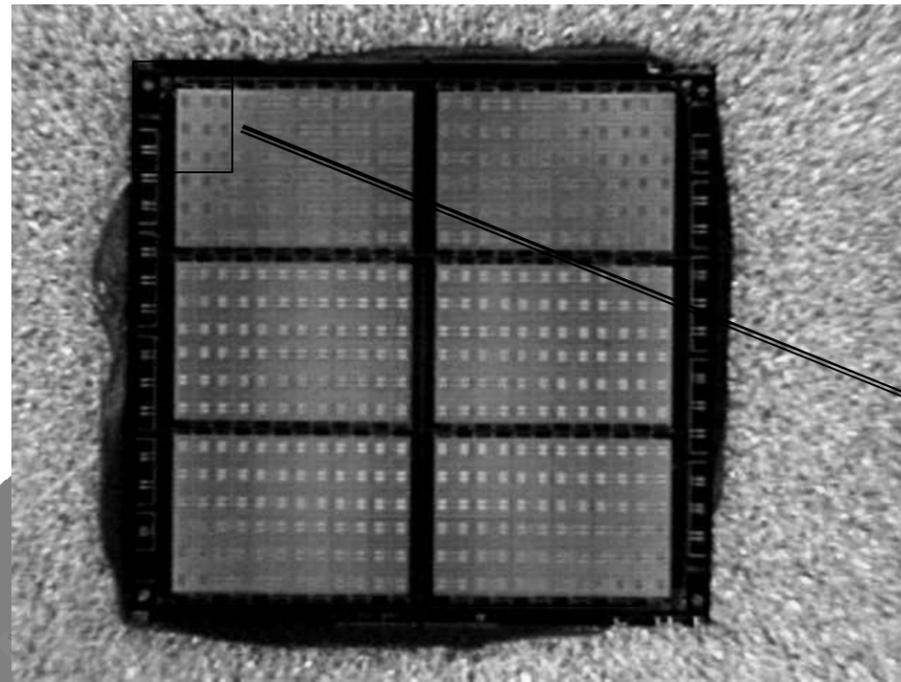
August 22, 2003

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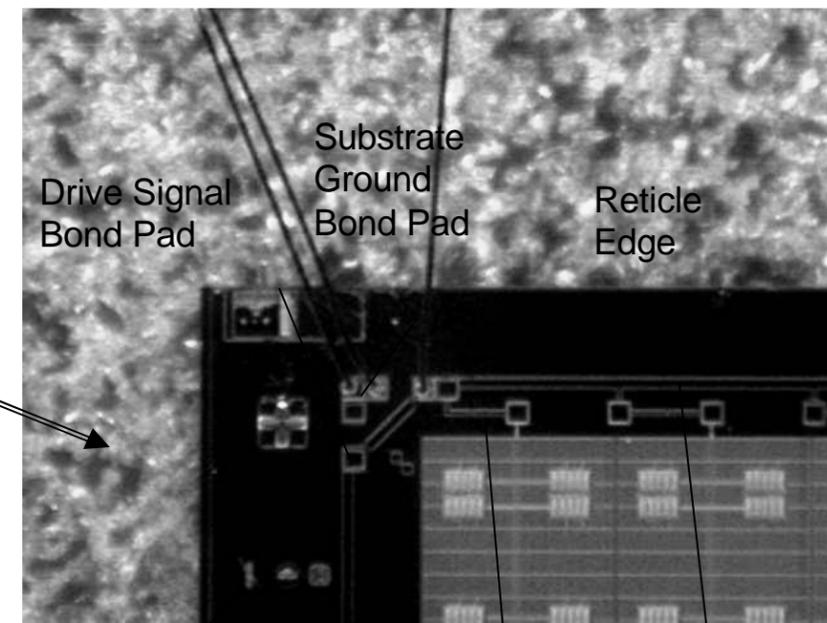
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# MEMS Shutters Flight Design



11.8 mm



- All Building Blocks connected to a single Bus with 20 mA Fuse connect to buried Interconnects
- Dual Bond Pads for Bus and Ground at corners

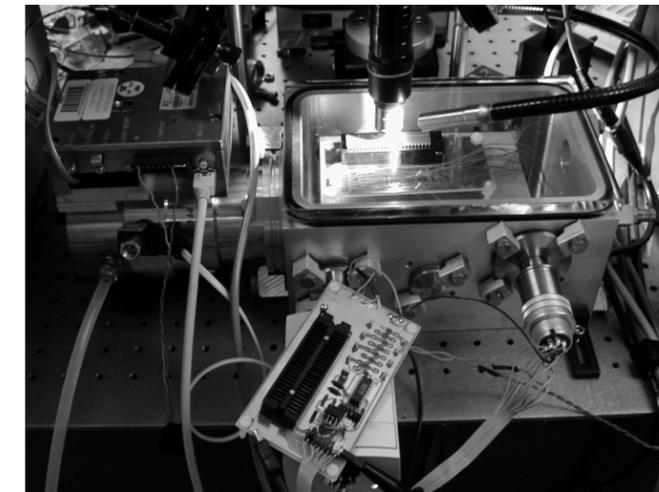
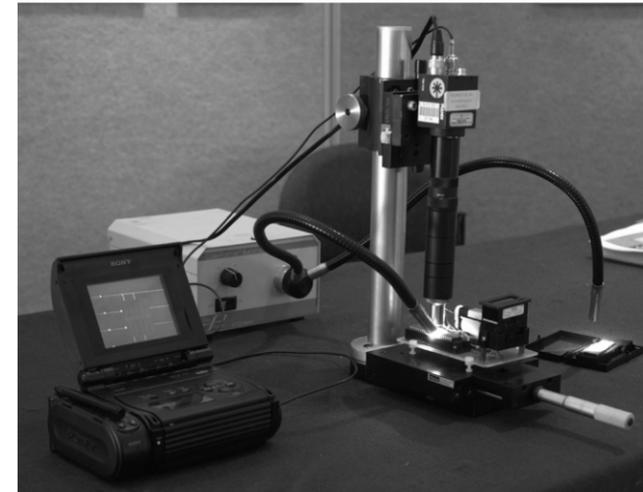


# MEMS Shutters

## Current Status

- Final generation shutter die delivered, 12 wafers (+ 1 test wafer), 69 die/wafer
  - All process-steps performed and verified on test wafer
  - Test wafer dies mounted and tested
- Performance-Testing on Prototype
  - Endurance testing in Air (> 1 year)
  - Vacuum testing (> 3 Million cycles)
  - Temperature Testing in Vacuum
    - High: +80°C
    - Low: - 130°C
    - 6 Temperature Cycling: - 40 °C to +80 °C
  - IR Emissivity

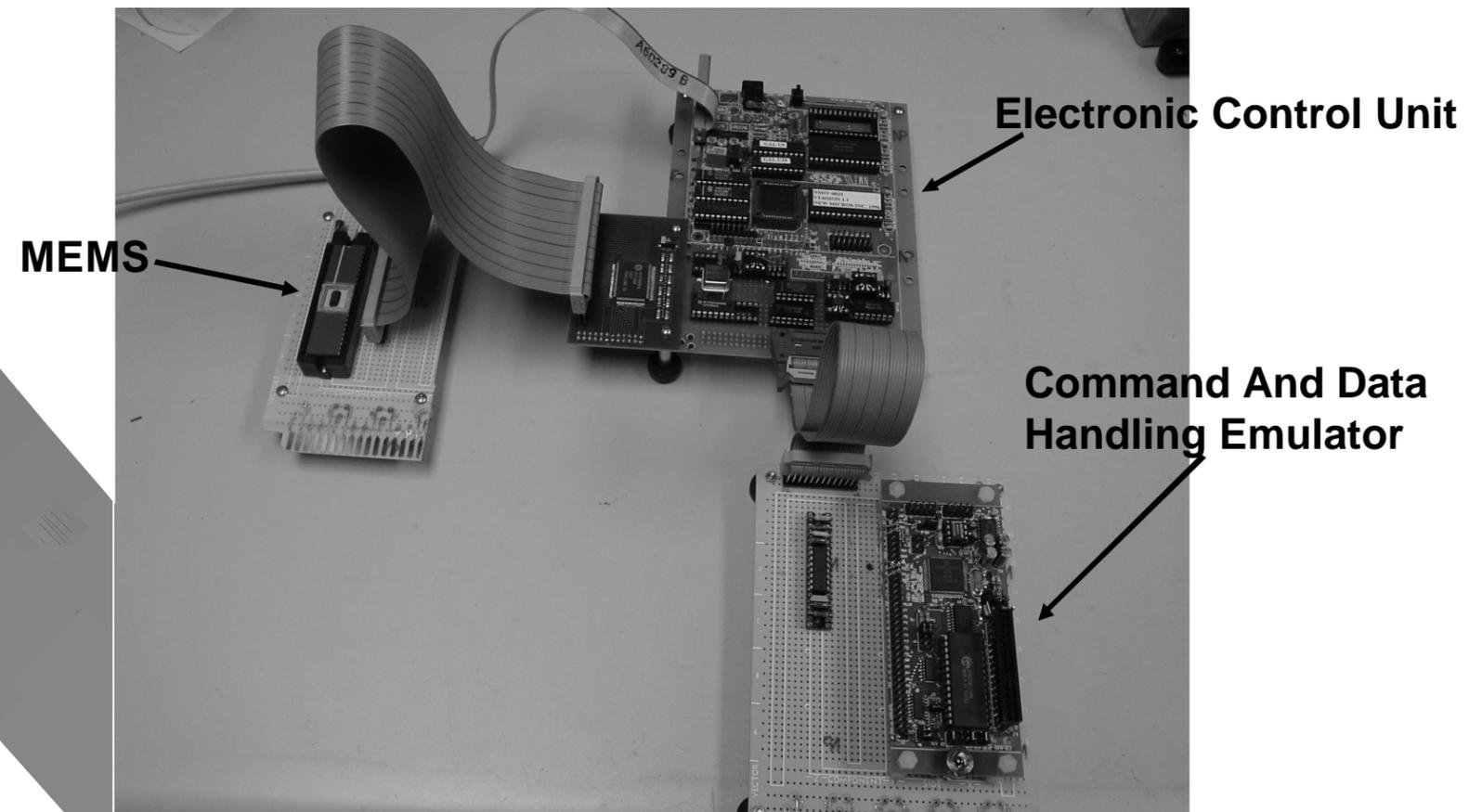
Ambient



Vacuum



# MEMS Shutters Current Status





# MEMS Shutters

## Milestone/Schedule

- All milestones consistent with and support ST-5 project schedule.
- Electronics breadboard to NASA for FLATSAT testing – 25 January 2003.
- October - November 2003 - Qualification Testing of Unit 1
- November - December 2003 - Acceptance Testing of Units 2 and 3
- December 2003 – Unit 1 shipped to GSFC
- January 2004 – Units 2 and 3 shipped to GSFC



## Major Issues/Concerns

- Initially started out with two other VEC technologies that had sealing problems and could not survive vacuum
  - Electrochromic
  - Electrophoretic
- Difficulty finding Rad-hard 5 Volt parts
  - Expensive
  - Long lead times
- Change in MEMS design due to hinge failures resulted in reduced performance
- Funding has been the major issue
  - Project wouldn't pick up funding until technology was at TRL 5
  - Technologies started out as concepts with very little funding
- Companies not experienced in producing hardware requiring lots of assistance/support.



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